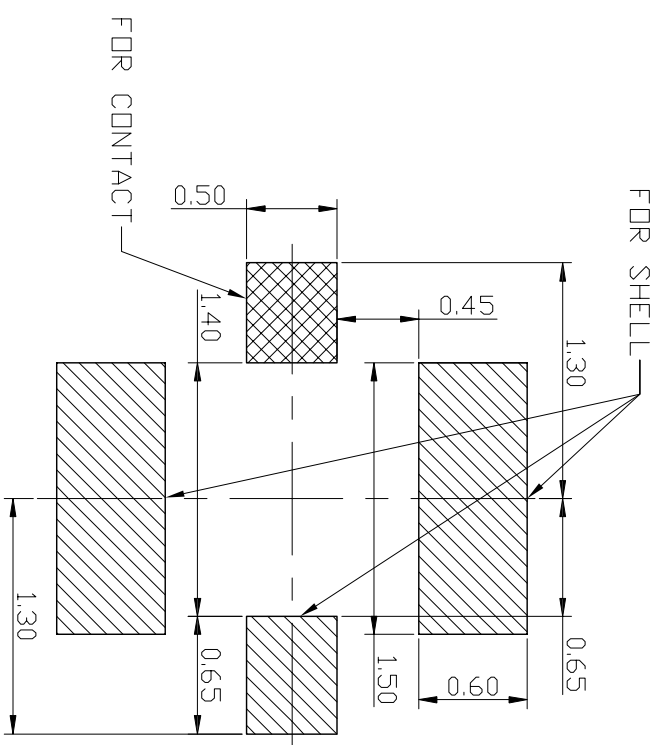
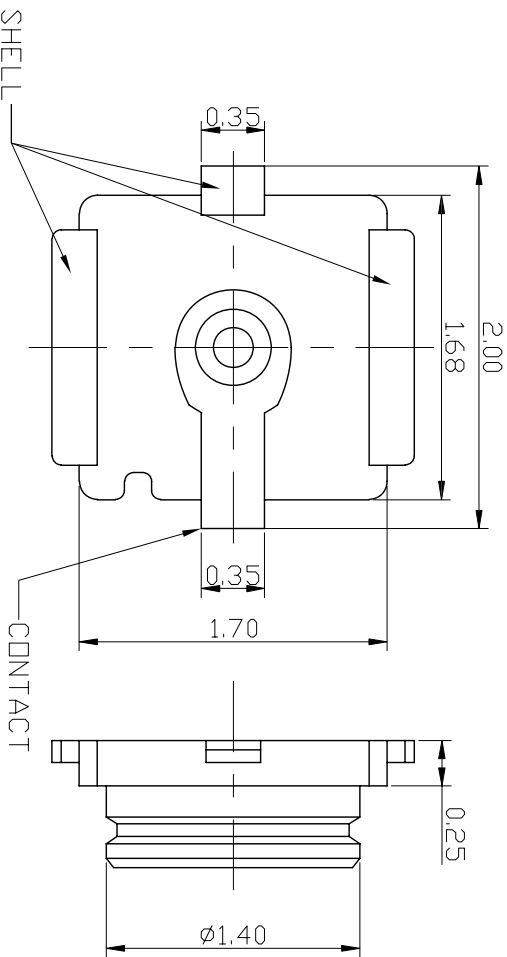
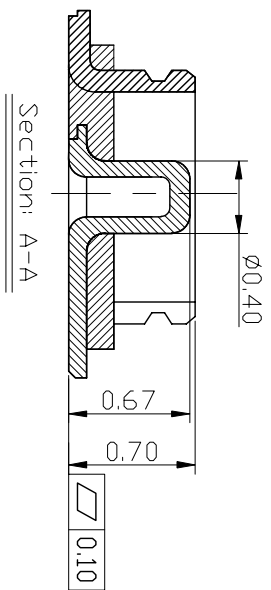
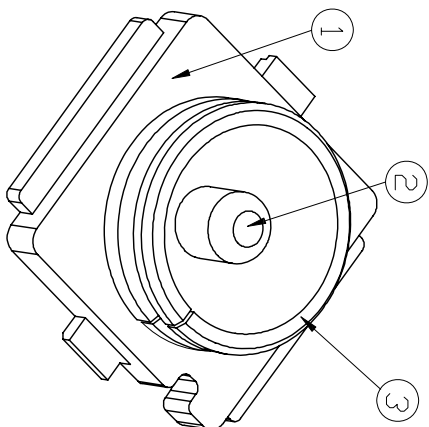
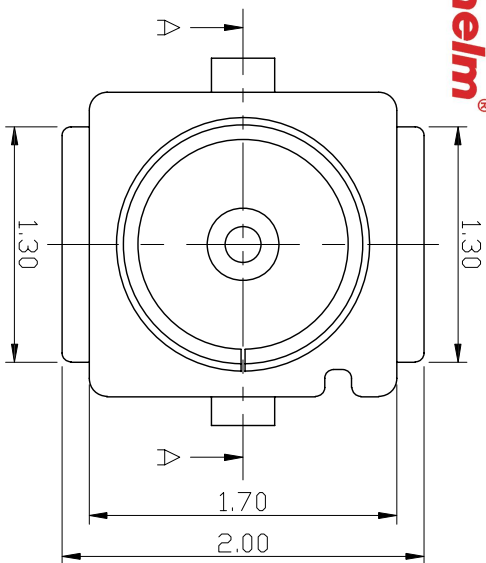


REV	ECN NO.	APPD
A	ECN1211001	MAX



Contact Pad
 Shell Pad

PCB Layout

NOTE: UNLESS OTHERWISE SPECIFIED

1. DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994.
2. DIMENSION MARKED WITH "▲" SHOULD SPECIFIED ON INSPECTION PLAN.
3. CONTACT RETENTION FORCE: 0.2 N MIN.
4. CONTACT MATERIAL: COPPER ALLOY.
5. INSULATOR: HIGH TEMPERATURE PLASTIC UL94 V-0.
6. LOW PROFILE: 1.5MM MAX. MATING HEIGHT.
7. APPLICATION FREQUENCY UP TO 6 G HZ.

ITEM	DESCRIPTION	QTY	MATERIAL	FINISH	REMARK
3	SHELL	1	COPPER ALLOY	Ni: 50u"~100u"/Tin Plating	
2	CONTACT	1	COPPER ALLOY	Ni: 50u"~100u"/Gold Flash	
1	HOUSING	1	LGR(BLACK)	UL94V-0	

深圳市金航标电子有限公司 WWW.BDS666.COM

型号: KH-IPEX3-2020

0755-83044319

DWG NO.:

XX± 0.25	XX± 3'	CHKD: Max 11/2'12	UNITS	SCALE	SHEET	REV.
.XXX± 1'	XXX± 1'	DR: Andy 11/2'12	mm	1:1	1/1	A

PART(FIG):